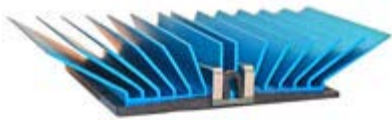


BGA Heat Sink - High Performance maxiFLOW/superGRIP



ATS Part#: **ATS-X50400G-C1-R0**
Description: 40.00 x 40.00 x 12.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP

Heat Sink Type: **maxiFLOW**
Heat Sink Attachment: **superGRIP**
Equivalent Part Number: **N/A**

**Image above is for illustration purpose only.*

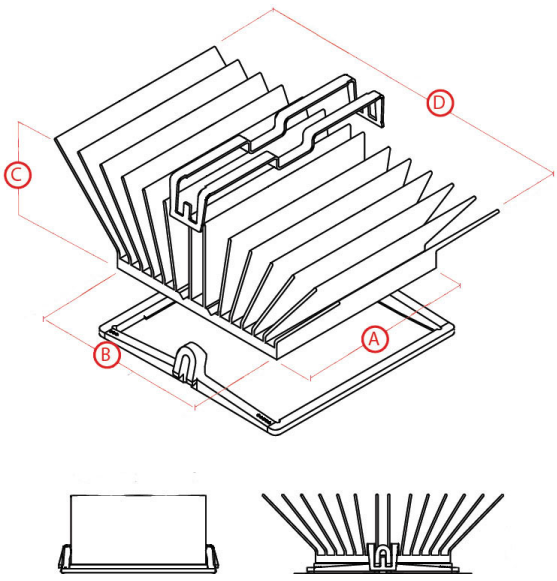
Features & Benefits

- Designed for 40 x 40 mm components
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	2.6 °C/W	2 °C/W	1.8 °C/W	1.6 °C/W	1.4 °C/W	1.3 °C/W	1.2 °C/W
	Ducted Flow	2	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	40.00 mm	40.00 mm	12.50 mm	69.2 mm	T766	BLUE-ANODIZED
<p>Notes:</p> <ul style="list-style-type: none">• Dimension A and B refer to component size.• Dimension C is the heat sink height from the bottom of the base to the top of the fin field.• Thermal performance data are provided for reference only. Actual performance may vary by application.• ATS reserves the right to update or change its products without notice to improve the design or performance.• ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.• Contact ATS to learn about custom options available.						

**Image above is for illustration purpose only.*

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